

# SN54CDC341 1-LINE TO 8-LINE CLOCK DRIVER

SGAS005A – MARCH 1996 – REVISED JULY 1997

- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Eight Outputs
- Distributed  $V_{CC}$  and Ground Pins Reduce Switching Noise
- High-Drive Outputs ( $-48\text{-mA } I_{OH}$ ,  $48\text{-mA } I_{OL}$ )
- State-of-the-Art *EPIC-II B*™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Ceramic Flatpacks (W), Ceramic Chip Carriers (FK), and Ceramic (J) 300-mil DIPS

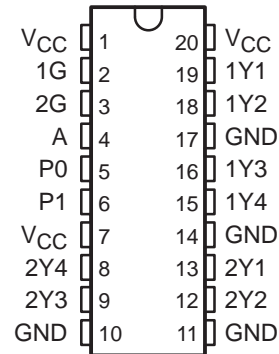
## description

The SN54CDC341 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a low state regardless of the A input.

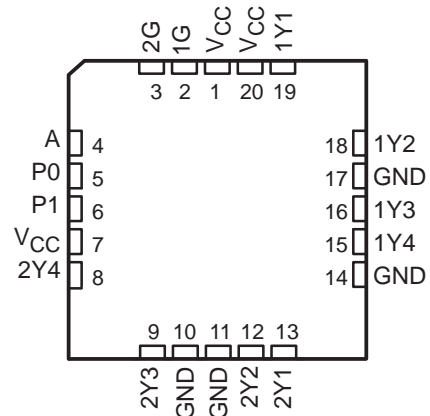
The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The SN54CDC341 is characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ .

J OR W PACKAGE  
(TOP VIEW)



FK PACKAGE  
(TOP VIEW)



FUNCTION TABLE

INPUTS			OUTPUTS	
1G	2G	A	1Y1–1Y4	2Y1–2Y4
X	X	L	L	L
L	L	H	L	L
L	H	H	L	H
H	L	H	H	L
H	H	H	H	H



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**TEXAS  
INSTRUMENTS**

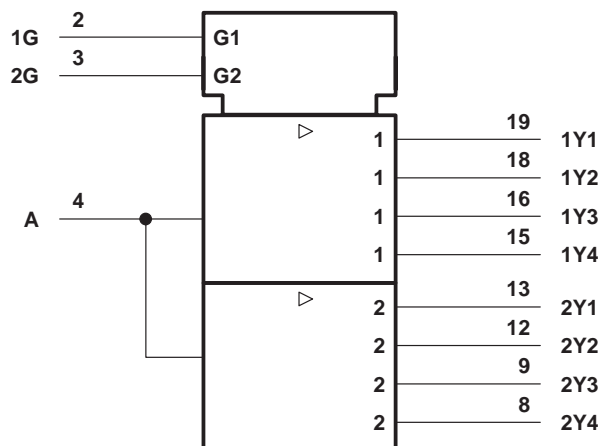
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# SN54CDC341 1-LINE TO 8-LINE CLOCK DRIVER

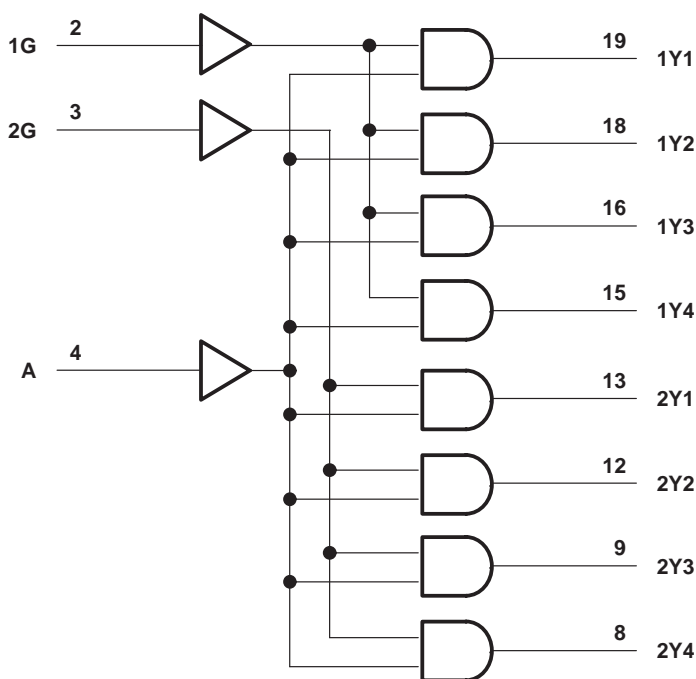
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## logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



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**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 7 V
Voltage range applied to any output in the high state or power-off state, $V_O$ (see Note 1) .....	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, $I_O$ .....	96 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ ) .....	–18 mA
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

**recommended operating conditions (see Note 2)**

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		V
$V_{IL}$	Low-level input voltage		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current		–48	mA
$I_{OL}$	Low-level output current		48	mA
$f_{clock}$	Input clock frequency	One output bank loaded		MHz
		Both output banks loaded		
$T_A$	Operating free-air temperature	–55	125	°C

NOTE 2: Unused pins (input or I/O) must be held high or low.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
$V_{IK}$	$V_{CC} = 4.5$ V,	$I_I = -18$ mA		–1.2	V
$V_{OH}$	$V_{CC} = 4.5$ V,	$I_{OH} = -3$ mA	2.5		V
	$V_{CC} = 5$ V,	$I_{OH} = -3$ mA	3		
	$V_{CC} = 4.5$ V,	$I_{OH} = -48$ mA	2		
$V_{OL}$	$V_{CC} = 4.5$ V,	$I_{OL} = 48$ mA		0.5	V
$I_I$	$V_{CC} = 5.5$ V,	$V_I = V_{CC}$ or GND		$\pm 1$	$\mu$ A
$I_O^\ddagger$	$V_{CC} = 5.5$ V,	$V_O = 2.5$ V	–50	–200	mA
$I_{CC}$	$V_{CC} = 5.5$ V, $V_I = V_{CC}$ or GND	$I_O = 0$ ,	Outputs high		mA
			Outputs low		
$C_i$	$V_I = 2.5$ V or 0.5 V				pF

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.



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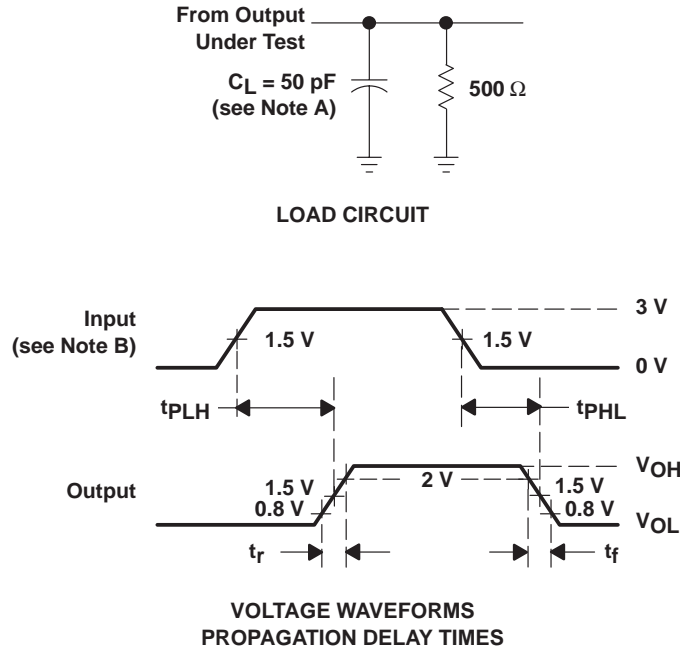
### switching characteristics, $C_L = 50 \text{ pF}$ (see Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	PACKAGE	$V_{CC} = 5 \text{ V}, T_A = 25^\circ\text{C}$			$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}, T_A = -55^\circ\text{C to } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
$t_{PLH}$	A	Y	All	2.3	6.7	1.8	7	ns	
$t_{PHL}$				3.6	6.3	3.3	7		
$t_{PLH}$	G	Y	All	1.6	4.1	1.3	4.7	ns	
$t_{PHL}$				2.3	4.4	1.8	4.9		
$t_{sk(o)}$	A	Y	J		1.8		1.9	ns	
			W		0.7		1.9		
			FK		0.6		0.8		
	G	Y	J		0.9		0.9	ns	
			W		0.5		1.2		
			FK		0.6		0.7		
$t_{sk(p)}$	A	Y	J		1.7		1.7	ns	
			W		1.4		1.7		
			FK		1.7		2.1		
	G	Y	J		1		1	ns	
			W		0.6		1.3		
			FK		1.3		1.8		
$t_{sk(pr)}^\dagger$	A or G	Y			1.2		1.2	ns	

$^\dagger t_{sk(pr)}$  is guaranteed across the full voltage and temperature range but is measured only at 25C,  $V_{CC} = 5 \text{ V}$ , using the A inputs.

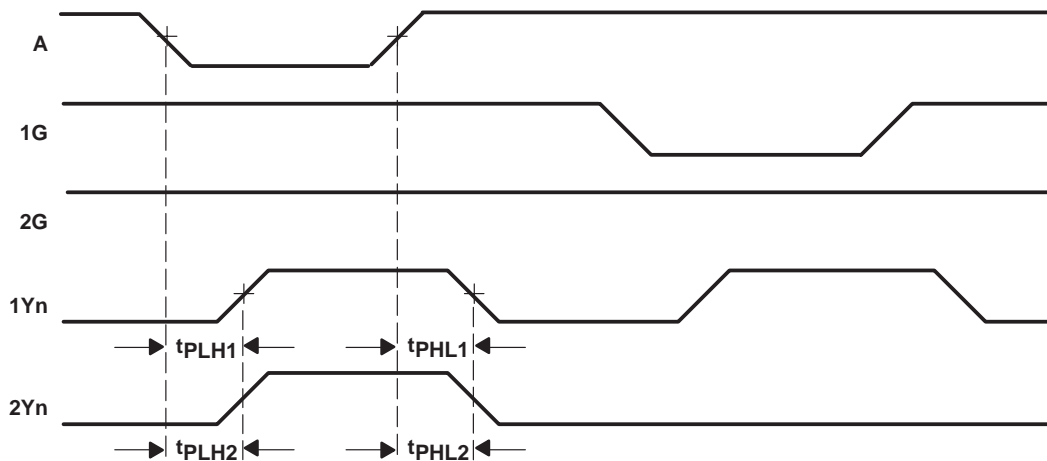


PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .

Figure 1. Load Circuit and Voltage Waveforms



- NOTES: A. Output skew,  $t_{sk(o)}$ , is calculated as the greater of:  
– The difference between the fastest and slowest of  $t_{PLHn}$  ( $n = 1, 2$ )  
– The difference between the fastest and slowest of  $t_{PHLn}$  ( $n = 1, 2$ )  
B. Pulse skew,  $t_{sk(p)}$ , is calculated as the greater of  $|t_{PLHn} - t_{PHLn}|$  ( $n = 1, 2$ ).  
C. Process skew,  $t_{sk(pr)}$ , is calculated as the greater of:  
– The difference between the fastest and slowest of  $t_{PLHn}$  ( $n = 1, 2$ ) across multiple devices under identical operating conditions  
– The difference between the fastest and slowest of  $t_{PHLn}$  ( $n = 1, 2$ ) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of  $t_{sk(o)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$

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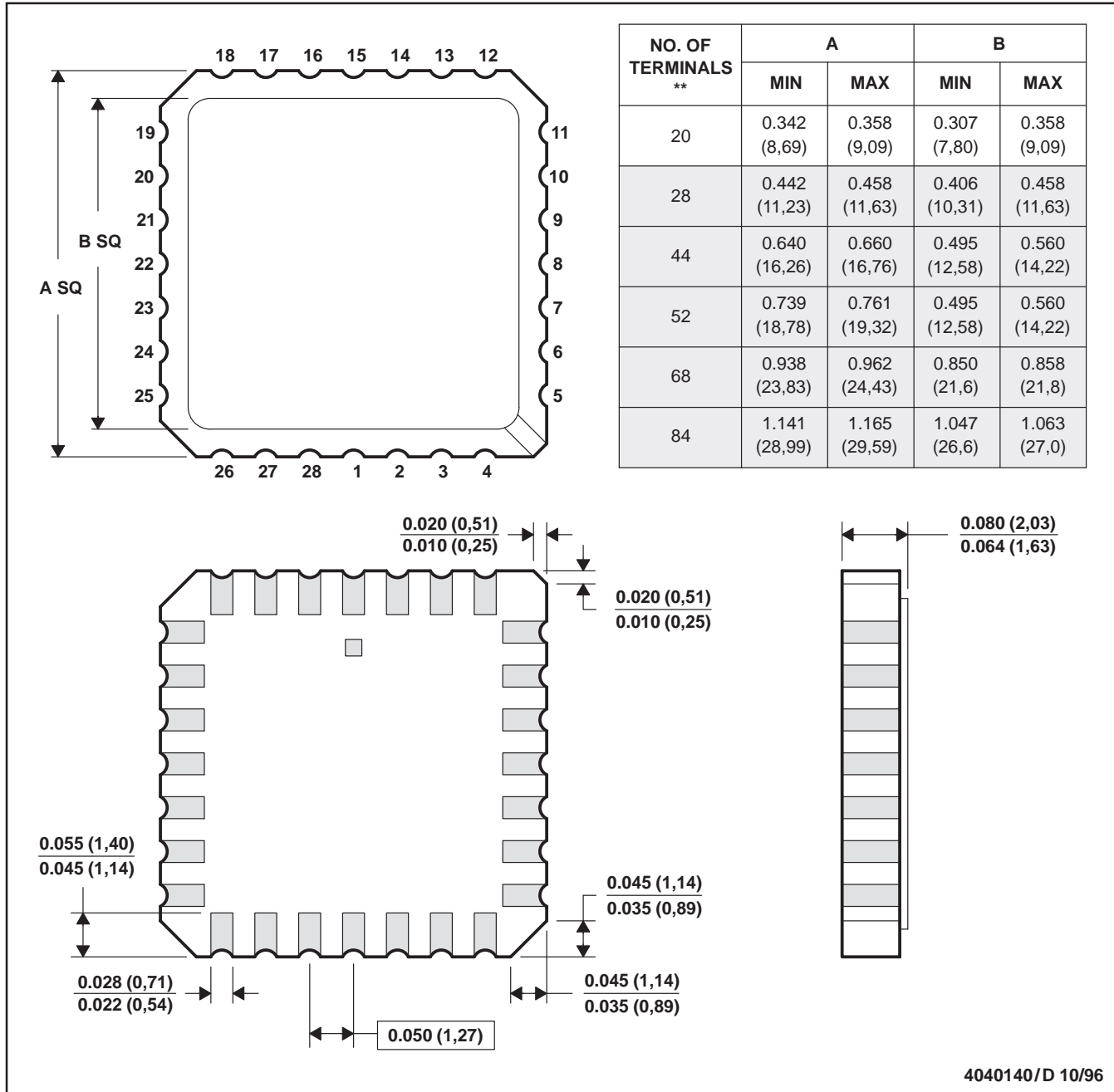
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## MECHANICAL INFORMATION

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004



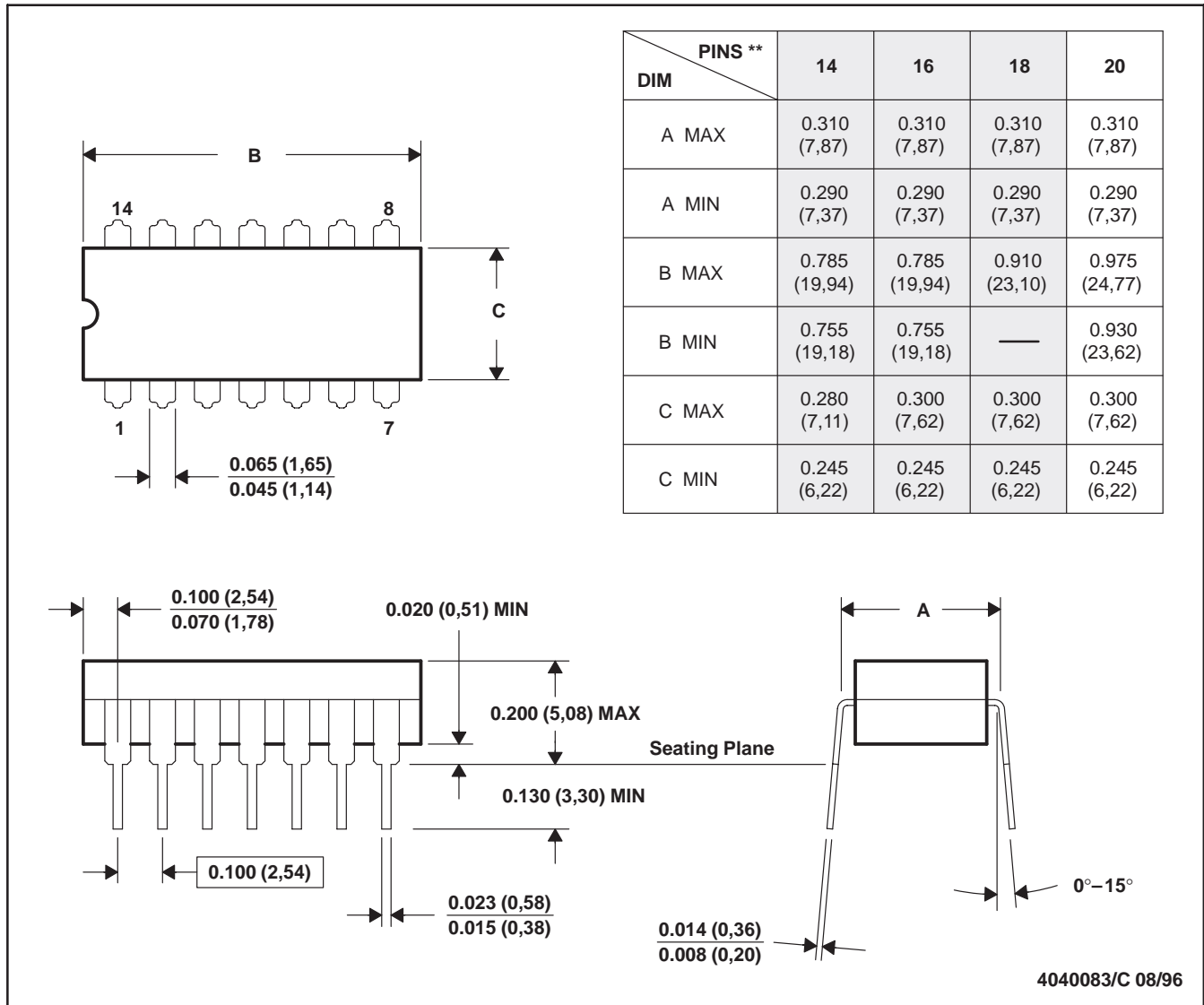
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MECHANICAL INFORMATION

J (R-GDIP-T\*\*)

CERAMIC DUAL-IN-LINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
 E. Falls within MIL-STD-1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, and GDIP1-T20

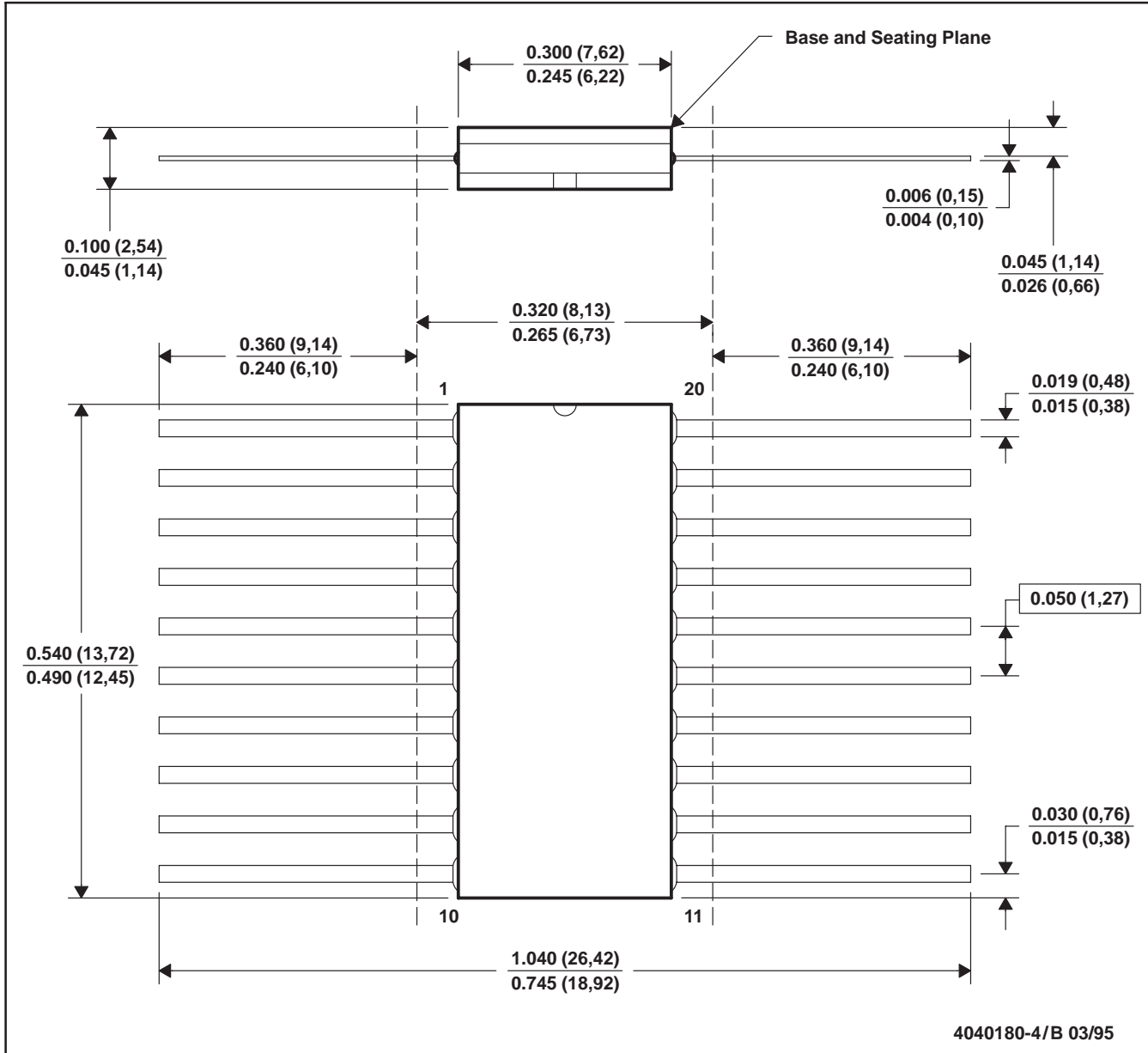
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## MECHANICAL INFORMATION

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a ceramic lid using glass frit.  
 D. Index point is provided on cap for terminal identification only.  
 E. Falls within MIL-STD-1835 GDFP2-F20



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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SNJ54CDC341FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54CDC341J	OBSOLETE	CDIP	J	20		TBD	Call TI	Call TI
SNJ54CDC341W	OBSOLETE	CFP	W	20		TBD	Call TI	Call TI

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

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<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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